

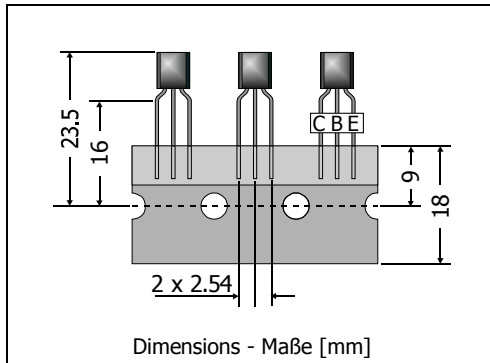
2N3904

NPN

Si-Epitaxial-Planar Switching Transistors
Si-Epitaxial-Planar Schalttransistoren

NPN

Version 2010-02-09


 Power dissipation
Verlustleistung

625 mW

 Plastic case
Kunststoffgehäuse
TO-92
(10D3)

Weight approx. – Gewicht ca.

0.18 g

 Plastic material has UL classification 94V-0
Gehäusematerial UL94V-0 klassifiziert

 Standard packaging taped in ammo pack
Standard Lieferform gegurtet in Ammo-Pack

Maximum ratings (T_A = 25°C)
Grenzwerte (T_A = 25°C)

| | | | 2N3904 |
|--|--------|------------------|----------------------|
| Collector-Emitter-volt. – Kollektor-Emitter-Spannung | B open | V _{CEO} | 40 V |
| Collector-Base-voltage – Kollektor-Basis-Spannung | E open | V _{CB0} | 60 V |
| Emitter-Base-voltage – Emitter-Basis-Spannung | C open | V _{EB0} | 6 V |
| Power dissipation – Verlustleistung | | P _{tot} | 625 mW ¹⁾ |
| Collector current – Kollektorstrom (dc) | | I _C | 200 mA |
| Junction temperature – Sperrschichttemperatur | | T _j | -55...+150°C |
| Storage temperature – Lagerungstemperatur | | T _S | -55...+150°C |

Characteristics (T_j = 25°C)
Kennwerte (T_j = 25°C)

| | | Min. | Typ. | Max. |
|--|-----------------|----------------------|-------------|--------------------|
| DC current gain – Kollektor-Basis-Stromverhältnis ²⁾ | | | | |
| I _C = 0.1 mA, V _{CE} = 1 V | h _{FE} | 4070 | – | – |
| I _C = 1 mA, V _{CE} = 1 V | h _{FE} | 100 | – | – |
| I _C = 10 mA, V _{CE} = 1 V | h _{FE} | 60 | – | 300 |
| I _C = 50 mA, V _{CE} = 1 V | h _{FE} | 30 | – | – |
| I _C = 100 mA, V _{CE} = 1 V | h _{FE} | – | – | – |
| h-Parameters at/bei V _{CE} = 10 V, - I _C = 1 mA, f = 1 kHz | | | | |
| Small signal current gain – Kleinsignal-Stromverstärkung | h _{fe} | 100 | – | 400 |
| Input impedance – Eingangs-Impedanz | h _{ie} | 1 kΩ | – | 10 kΩ |
| Output admittance – Ausgangs-Leitwert | h _{oe} | 1 μS | – | 40 μS |
| Reverse voltage transfer ratio – Spannungsrückwirkung | h _{re} | 0.5*10 ⁻⁴ | – | 8*10 ⁻⁴ |

1 Mounted on P.C. board with 3 mm² copper pad at each terminal
Montage auf Leiterplatte mit 3 mm² Kupferbelag (Löt-pad) an jedem Anschluss

2 Tested with pulses t_p = 300 μs, duty cycle ≤ 2% – Gemessen mit Impulsen t_p = 300 μs, Schaltverhältnis ≤ 2%

Characteristics (T_j = 25°C)
Kennwerte (T_j = 25°C)

| | | Min. | Typ. | Max. |
|---|--|------------------|-------------------------|-------------|
| Collector-Emitter saturation voltage – Kollektor-Sättigungsspannung ²⁾ | | | | |
| I _C = 10 mA, I _B = 1 mA | V _{CEsat} | – | – | 0.2 V |
| I _C = 50 mA, I _B = 5 mA | V _{CEsat} | – | – | 0.3 V |
| Base-Emitter saturation voltage – Basis-Sättigungsspannung ²⁾ | | | | |
| I _C = 10 mA, I _B = 1 mA | V _{BEsat} | 0.65 V | – | 0.65 V |
| I _C = 50 mA, I _B = 5 mA | V _{BEsat} | – | – | 0.95 V |
| Collector-Base cutoff current – Kollektor-Basis-Reststrom | | | | |
| V _{CE} = 30 V, V _{EB} = 3 V | I _{CBX} | – | – | 50 nA |
| Emitter-Base cutoff current – Emitter-Basis-Reststrom | | | | |
| - V _{CE} = 30 V, - V _{EB} = 3 V | I _{EBV} | – | – | 50 nA |
| Gain-Bandwidth Product – Transitfrequenz | | | | |
| I _C = 10 mA, V _{CE} = 20 V, f = 100 MHz | f _T | 300 MHz | – | – |
| Collector-Base Capacitance – Kollektor-Basis-Kapazität | | | | |
| V _{CB} = 5 V, I _E = i _e = 0, f = 1 MHz | C _{CB0} | – | – | 4 pF |
| Emitter-Base Capacitance – Emitter-Basis-Kapazität | | | | |
| V _{EB} = 0.5 V, I _C = i _c = 0, f = 1 MHz | C _{EBO} | – | – | 8 pF |
| Noise figure – Rauschzahl | | | | |
| V _{CE} = 5 V, I _C = 1 μA, R _G = 1 kΩ, f = 1 kHz | F | – | – | 5 dB |
| Switching times – Schaltzeiten (between 10% and 90% levels) | | | | |
| delay time | V _{CC} = 3 V, V _{BE} = 0.5 V | t _d | – | – |
| rise time | I _C = 10 mA, I _{B1} = 1 mA | t _r | – | – |
| storage time | V _{CC} = 3 V, I _C = 10 mA, | t _s | – | – |
| fall time | I _{B1} = I _{B2} = 1 mA | t _f | – | – |
| Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft | | R _{thA} | < 200 K/W ¹⁾ | |
| Recommended complementary PNP transistors Empfohlene komplementäre PNP-Transistoren | | 2N3906 | | |

²⁾ Tested with pulses t_p = 300 μs, duty cycle ≤ 2% – Gemessen mit Impulsen t_p = 300 μs, Schaltverhältnis ≤ 2%

¹⁾ Mounted on P.C. board with 3 mm² copper pad at each terminal
Montage auf Leiterplatte mit 3 mm² Kupferbelag (Löt-pad) an jedem Anschluss